

## ABSTRACT

The invention relates to a method for forming a multilayer circuit structure and to a substrate having a multilayer circuit structure. Its object is to increase the adhesion of the conductor circuit layer while the surface of the electrical insulating layer is kept smooth. A curable composition film containing an insulating polymer and a curing agent is formed as the outermost layer of an inner layer board, then a compound having a structure capable of coordinating to a metal is brought into contact with the surface of the curable composition film, then the curable composition film is cured to form an electrical insulating layer, then the surface of the resulting electrical insulating layer is hydrophilicated, then a metal thin-film layer of an ethylenediaminetetraacetate-copper complex is formed on the surface of the electrical insulating layer, and then a conductor circuit layer containing the metal thin-film layer is formed.